ontact Name	IPC Web Site for Inf http://www.ipc.org/ mation			lard	Form Type * Distribute				Homogeneous Materia	als and Mfg Information			
ompany name* semi ontact Name	mation		Commons					Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					
semi ontact Name			Commony										
ontact Name			Company unique ID			Unique ID Authority			Response Date*				
		onsemi								2024-04-20			
	Contact Name Title - Contact				et P		Phone - Contact*			Email - Contact*			
Product-Env-Stewards Product-Env-Stewards				Product Enviro Compliance		NA	NA			Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative		Phone	Phone - Representative*			Email - Representative*				
Product-Env-Stewards Produ			Product Enviro Compliance		NA	NA			Product-Env-Stewards@onsemi.com				
Reques	Requester Item Number Mi		Mfr Item Number Mfr Item Name			Effec	Effective Date		Manufacturing Site	Weight*	UOM	Unit Type	
		NTSV30H100ECTG 30A, 100V LOW I Schottky Rectifier		LEAKAGE Trench	2024-	-04-20		CNC	1960.702	mg	Each		
anufacturing	g Proccess Informat	tion											
Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 MSL		STD-020 MSL Rating	P	Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed		C	CU Alloy NA		Α	0 C 30			seconds 3				
mments													

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not originate agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to su										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.2	mg	Supplier	Silicon (Si)	7440-21-3		2.2	mg
Die Attach	0.212	mg	A	Lead (Pb)	7439-92-1	7a	0.1908	mg
			Supplier	Tin (Sn)	7440-31-5		0.0212	mg
Lead Frame	1271.74		Supplier	Iron (Fe)	7439-89-6		2.4163	mg
			Supplier	Copper (Cu)	7440-50-8		1269.1965	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1272	mg
Mold Compound-Black	644.0			Epoxy Phenol Resin	proprietary data		54.74	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		9.66	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		557.06	mg
			Supplier	Bisphenol A, Epichlorohydrin polymer	90598-46-2, 25068- 38-6		22.54	mg
Plating	42.4	mg	Supplier	Tin (Sn)	7440-31-5		42.4	mg
Wire Bond - Al	0.15	mg	Supplier	Aluminum (Al)	7429-90-5		0.15	mg